

Johan Liu

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/2361474/publications.pdf>

Version: 2024-02-01

163
papers

3,966
citations

109321

35
h-index

155660

55
g-index

166
all docs

166
docs citations

166
times ranked

4724
citing authors

#	ARTICLE	IF	CITATIONS
1	Novel nanostructured thermal interface materials: a review. <i>International Materials Reviews</i> , 2018, 63, 22-45.	19.3	261
2	Graphene related materials for thermal management. <i>2D Materials</i> , 2020, 7, 012001.	4.4	161
3	Effect of Ag particle size on electrical conductivity of isotropically conductive adhesives. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 1999, 22, 299-302.	1.4	157
4	Synthesis of graphene quantum dots and their applications in drug delivery. <i>Journal of Nanobiotechnology</i> , 2020, 18, 142.	9.1	142
5	Functionalization mediates heat transport in graphene nanoflakes. <i>Nature Communications</i> , 2016, 7, 11281.	12.8	123
6	Improved Heat Spreading Performance of Functionalized Graphene in Microelectronic Device Application. <i>Advanced Functional Materials</i> , 2015, 25, 4430-4435.	14.9	117
7	Tailoring the Thermal and Mechanical Properties of Graphene Film by Structural Engineering. <i>Small</i> , 2018, 14, e1801346.	10.0	106
8	Bioactive 3D cell culture system minimizes cellular stress and maintains the <i>in vivo</i> -like morphological complexity of astroglial cells. <i>Glia</i> , 2013, 61, 432-440.	4.9	100
9	Thermal chemical vapor deposition grown graphene heat spreader for thermal management of hot spots. <i>Carbon</i> , 2013, 61, 342-348.	10.3	96
10	Cellulose-derived carbon nanofibers/graphene composite electrodes for powerful compact supercapacitors. <i>RSC Advances</i> , 2017, 7, 45968-45977.	3.6	76
11	Stretchable Thermoelectric Generators Metallized with Liquid Alloy. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 15791-15797.	8.0	72
12	Nanoparticles of SnAgCu lead-free solder alloy with an equivalent melting temperature of SnPb solder alloy. <i>Journal of Alloys and Compounds</i> , 2009, 484, 777-781.	5.5	71
13	Carbon Nanotube Through-Silicon Via Interconnects for Three-Dimensional Integration. <i>Small</i> , 2011, 7, 2313-2317.	10.0	69
14	Through-Silicon Vias Filled With Densified and Transferred Carbon Nanotube Forests. <i>IEEE Electron Device Letters</i> , 2012, 33, 420-422.	3.9	67
15	Synthesis and applications of two-dimensional hexagonal boron nitride in electronics manufacturing. <i>Electronic Materials Letters</i> , 2016, 12, 1-16.	2.2	67
16	Tensile properties and microstructural characterization of Sn _{0.7} Cu _{0.4} Co bulk solder alloy for electronics applications. <i>Journal of Alloys and Compounds</i> , 2008, 457, 97-105.	5.5	55
17	Through silicon vias filled with planarized carbon nanotube bundles. <i>Nanotechnology</i> , 2009, 20, 485203.	2.6	54
18	Direct Photolithographic Patterning of Electrospun Films for Defined Nanofibrillar Microarchitectures. <i>Langmuir</i> , 2010, 26, 2235-2239.	3.5	52

#	ARTICLE	IF	CITATIONS
19	Stem cell responses to plasma surface modified electrospun polyurethane scaffolds. <i>Nanomedicine: Nanotechnology, Biology, and Medicine</i> , 2014, 10, e949-e958.	3.3	50
20	Efficient surface modification of carbon nanotubes for fabricating high performance CNT based hybrid nanostructures. <i>Carbon</i> , 2017, 111, 402-410.	10.3	50
21	Ultrafast Transfer of Metal-Enhanced Carbon Nanotubes at Low Temperature for Large-Scale Electronics Assembly. <i>Advanced Materials</i> , 2010, 22, 5039-5042.	21.0	48
22	Nanoparticles of the Lead-free Solder Alloy Sn-3.0Ag-0.5Cu with Large Melting Temperature Depression. <i>Journal of Electronic Materials</i> , 2009, 38, 351-355.	2.2	47
23	Surface characterisation of oxygen plasma treated electrospun polyurethane fibres and their interaction with red blood cells. <i>European Polymer Journal</i> , 2012, 48, 472-482.	5.4	47
24	Enhanced electrochemical performance of three-dimensional graphene/carbon nanotube composite for supercapacitor application. <i>Journal of Alloys and Compounds</i> , 2020, 820, 153114.	5.5	47
25	Vertically Stacked Carbon Nanotube-Based Interconnects for Through Silicon Via Application. <i>IEEE Electron Device Letters</i> , 2015, 36, 499-501.	3.9	44
26	Graphene oxide based coatings on nitinol for biomedical implant applications: effectively promote mammalian cell growth but kill bacteria. <i>RSC Advances</i> , 2016, 6, 38124-38134.	3.6	44
27	Thermodynamic assessment of the Sn-Co lead-free solder system. <i>Journal of Electronic Materials</i> , 2004, 33, 935-939.	2.2	43
28	Surface-Confined Synthesis of Silver Nanoparticle Composite Coating on Electrospun Polyimide Nanofibers. <i>Small</i> , 2011, 7, 3057-3066.	10.0	43
29	<sc>HB</sc>-EGF affects astrocyte morphology, proliferation, differentiation, and the expression of intermediate filament proteins. <i>Journal of Neurochemistry</i> , 2014, 128, 878-889.	3.9	43
30	Vertically aligned CNT-Cu nano-composite material for stacked through-silicon-via interconnects. <i>Nanotechnology</i> , 2016, 27, 335705.	2.6	43
31	Mechanical behaviour of sintered silver nanoparticles reinforced by SiC microparticles. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2019, 744, 406-414.	5.6	43
32	High temperature aging study of intermetallic compound formation of Sn-3.5Ag and Sn-4.0Ag-0.5Cu solders on electroless Ni(P) metallization. <i>Journal of Alloys and Compounds</i> , 2006, 425, 191-199.	5.5	42
33	Dry densification of carbon nanotube bundles. <i>Carbon</i> , 2010, 48, 3795-3801.	10.3	39
34	Scalable production of thick graphene film for next generation thermal management application. <i>Carbon</i> , 2020, 167, 270-277.	10.3	39
35	Templated Growth of Covalently Bonded Three-Dimensional Carbon Nanotube Networks Originated from Graphene. <i>Advanced Materials</i> , 2012, 24, 1576-1581.	21.0	37
36	Thermal Conductivity Enhancement of Coaxial Carbon@Boron Nitride Nanotube Arrays. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 14555-14560.	8.0	35

#	ARTICLE	IF	CITATIONS
37	Experimental and theoretical characterization of electrical contact in anisotropically conductive adhesive. IEEE Transactions on Advanced Packaging, 2000, 23, 15-21.	1.6	33
38	Two-dimensional hexagonal boron nitride as lateral heat spreader in electrically insulating packaging. Journal Physics D: Applied Physics, 2016, 49, 265501.	2.8	33
39	Review of current progress of thermal interface materials for electronics thermal management applications. , 2016, , .		32
40	Compact and low loss electrochemical capacitors using a graphite / carbon nanotube hybrid material for miniaturized systems. Journal of Power Sources, 2019, 412, 374-383.	7.8	32
41	Highly Oriented Graphite Aerogel Fabricated by Confined Liquid-Phase Expansion for Anisotropically Thermally Conductive Epoxy Composites. ACS Applied Materials & Interfaces, 2020, 12, 27476-27484.	8.0	32
42	Study of interfacial reactions in Sn ^{3.5} Ag ^{3.0} Bi and Sn ^{8.0} Zn ^{3.0} Bi sandwich structure solder joint with Ni(P)/Cu metallization on Cu substrate. Journal of Alloys and Compounds, 2007, 437, 169-179.	5.5	30
43	Paper-mediated controlled densification and low temperature transfer of carbon nanotube forests for electronic interconnect application. Microelectronic Engineering, 2013, 103, 177-180.	2.4	30
44	A REVIEW OF MICROWAVE CURING OF POLYMERIC MATERIALS. Journal of Electronics Manufacturing, 2000, 10, 181-189.	0.4	29
45	Process development and adhesion behavior of electroless copper on liquid crystal polymer (LCP) for electronic packaging application. IEEE Transactions on Electronics Packaging Manufacturing, 2002, 25, 273-278.	1.4	29
46	Electrical Conductive Characteristics of Anisotropic Conductive Adhesive Particles. Journal of Electronic Packaging, Transactions of the ASME, 2003, 125, 609-616.	1.8	29
47	Characterization and simulation of liquid phase exfoliated graphene-based films for heat spreading applications. Carbon, 2016, 106, 195-201.	10.3	28
48	Novel thermal interface materials: boron nitride nanofiber and indium composites for electronics heat dissipation applications. Journal of Materials Science: Materials in Electronics, 2014, 25, 2333-2338.	2.2	26
49	Polymer-metal nanofibrous composite for thermal management of microsystems. Materials Letters, 2012, 75, 229-232.	2.6	25
50	Organic Thin-Film Transistors with Anodized Gate Dielectric Patterned by Self-Aligned Embossing on Flexible Substrates. Advanced Functional Materials, 2012, 22, 1209-1214.	14.9	24
51	Modeling of the effective thermal conductivity of composite materials with FEM based on resistor networks approach. Microsystem Technologies, 2010, 16, 633-639.	2.0	23
52	Direct Chemical Vapor Deposition of Large-Area Carbon Thin Films on Gallium Nitride for Transparent Electrodes: A First Attempt. IEEE Transactions on Semiconductor Manufacturing, 2012, 25, 494-501.	1.7	23
53	A Novel Graphene Quantum Dot-Based mRNA Delivery Platform. ChemistryOpen, 2021, 10, 666-671.	1.9	23
54	Significance of intermediate production processes in life cycle assessment of electronic products assessed using a generic compact model. Journal of Cleaner Production, 2005, 13, 1269-1279.	9.3	22

#	ARTICLE	IF	CITATIONS
55	Carbon nanotubes for electronics manufacturing and packaging: from growth to integration. <i>Advances in Manufacturing</i> , 2013, 1, 13-27.	6.1	22
56	A new solder matrix nano polymer composite for thermal management applications. <i>Composites Science and Technology</i> , 2014, 94, 54-61.	7.8	21
57	A carbon fiber solder matrix composite for thermal management of microelectronic devices. <i>Journal of Materials Chemistry C</i> , 2014, 2, 7184-7187.	5.5	21
58	Tape-Assisted Transfer of Carbon Nanotube Bundles for Through-Silicon-Via Applications. <i>Journal of Electronic Materials</i> , 2015, 44, 2898-2907.	2.2	21
59	Egg albumen templated graphene foams for high-performance supercapacitor electrodes and electrochemical sensors. <i>Journal of Materials Chemistry A</i> , 2018, 6, 18267-18275.	10.3	21
60	Flexible Multifunctionalized Carbon Nanotubes-Based Hybrid Nanowires. <i>Advanced Functional Materials</i> , 2015, 25, 4135-4143.	14.9	20
61	Improving Thermal Transport at Carbon Hybrid Interfaces by Covalent Bonds. <i>Advanced Materials Interfaces</i> , 2018, 5, 1800318.	3.7	20
62	Selective growth of double-walled carbon nanotubes on gold films. <i>Materials Letters</i> , 2012, 72, 78-80.	2.6	19
63	Thermally Reduced Graphene Oxide/Carbon Nanotube Composite Films for Thermal Packaging Applications. <i>Materials</i> , 2020, 13, 317.	2.9	19
64	Electrical characterization of isotropic conductive adhesive under mechanical loading. <i>Journal of Electronic Materials</i> , 2002, 31, 916-920.	2.2	18
65	Theoretical Analysis of RF Performance of Anisotropic Conductive Adhesive Flip-Chip Joints. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2004, 27, 546-550.	1.3	18
66	Formation of three-dimensional carbon nanotube structures by controllable vapor densification. <i>Materials Letters</i> , 2012, 78, 184-187.	2.6	17
67	A High Performance Ag Alloyed Nano-scale n-type Bi ₂ Te ₃ Based Thermoelectric Material. <i>Materials Today: Proceedings</i> , 2015, 2, 610-619.	1.8	17
68	Interface and interconnection stresses in electronic assemblies – A critical review of analytical solutions. <i>Microelectronics Reliability</i> , 2017, 79, 206-220.	1.7	17
69	High porosity and light weight graphene foam heat sink and phase change material container for thermal management. <i>Nanotechnology</i> , 2020, 31, 424003.	2.6	17
70	Elevated thermoelectric figure of merit of n-type amorphous silicon by efficient electrical doping process. <i>Nano Energy</i> , 2018, 44, 89-94.	16.0	16
71	Finite Element Analysis to the Constitutive Behavior of Sintered Silver Nanoparticles Under Nanoindentation. <i>International Journal of Applied Mechanics</i> , 2018, 10, 1850110.	2.2	16
72	Properties of Undoped Few-Layer Graphene-Based Transparent Heaters. <i>Materials</i> , 2020, 13, 104.	2.9	16

#	ARTICLE	IF	CITATIONS
73	Effect of different temperature cycle profiles on the crack propagation and microstructural evolution of lead free solder joints of different electronic components. , 0, , .		15
74	Embedded Finâ€Like Metal/CNT Hybrid Structures for Flexible and Transparent Conductors. Small, 2016, 12, 1521-1526.	10.0	15
75	Mechanical and thermal characterization of a novel nanocomposite thermal interface material for electronic packaging. Microelectronics Reliability, 2016, 56, 129-135.	1.7	15
76	Effects of high temperature treatment of carbon nanotube arrays on graphite: increased crystallinity, anchoring and inter-tube bonding. Nanotechnology, 2020, 31, 455708.	2.6	15
77	Degradation of Carbon Nanotube Array Thermal Interface Materials through Thermal Aging: Effects of Bonding, Array Height, and Catalyst Oxidation. ACS Applied Materials & Interfaces, 2021, 13, 30992-31000.	8.0	15
78	Microwave-transmission, heat and temperature properties of electrically conductive adhesive. IEEE Transactions on Components and Packaging Technologies, 2003, 26, 193-198.	1.3	14
79	LCA of electronic products. International Journal of Life Cycle Assessment, 2004, 9, 45-52.	4.7	14
80	Understanding noninvasive charge transfer doping of graphene: a comparative study. Journal of Materials Science: Materials in Electronics, 2018, 29, 5239-5252.	2.2	14
81	LIFE CYCLE ASSESSMENT OF A TELECOMMUNICATIONS EXCHANGE. Journal of Electronics Manufacturing, 2000, 10, 147-160.	0.4	13
82	Controllable and fast synthesis of bilayer graphene by chemical vapor deposition on copper foil using a cold wall reactor. Chemical Engineering Journal, 2016, 304, 106-114.	12.7	13
83	Unusual tensile behaviour of fibre-reinforced indium matrix composite and its in-situ TEM straining observation. Acta Materialia, 2016, 104, 109-118.	7.9	13
84	Chemical vapor deposition grown graphene on Cu-Pt alloys. Materials Letters, 2017, 193, 255-258.	2.6	13
85	Surface Modification of Graphene for Use as a Structural Fortifier in Water-Borne Epoxy Coatings. Coatings, 2019, 9, 754.	2.6	13
86	Formulation and characterization of anisotropic conductive adhesive paste for microelectronics packaging applications. Journal of Electronic Materials, 2005, 34, 1420-1427.	2.2	12
87	A Highly Conductive Bimodal Isotropic Conductive Adhesive and Its Reliability. ECS Transactions, 2011, 34, 583-588.	0.5	12
88	The Effect of Functionalized Silver on Rheological and Electrical Properties of Conductive Adhesives. ECS Transactions, 2011, 34, 811-816.	0.5	12
89	Improved Interfacial Bonding Strength and Reliability of Functionalized Graphene Oxide for Cement Reinforcement Applications. Chemistry - A European Journal, 2020, 26, 6561-6568.	3.3	12
90	A lightweight and high thermal performance graphene heat pipe. Nano Select, 2021, 2, 364-372.	3.7	12

#	ARTICLE	IF	CITATIONS
91	Reliability Investigation of a Carbon Nanotube Array Thermal Interface Material. <i>Energies</i> , 2019, 12, 2080.	3.1	11
92	Graphene-Based Films: Fabrication, Interfacial Modification, and Applications. <i>Nanomaterials</i> , 2021, 11, 2539.	4.1	11
93	Aerosol Jet Printing of Graphene and Carbon Nanotube Patterns on Realistically Rugged Substrates. <i>ACS Omega</i> , 2021, 6, 34301-34313.	3.5	11
94	Coffinâ€Manson constant determination for a Snâ€Znâ€Bi leadâ€free solder joint. <i>Soldering and Surface Mount Technology</i> , 2006, 18, 4-11.	1.5	10
95	System-on-package: a broad perspective from system design to technology development. <i>Microelectronics Reliability</i> , 2003, 43, 1339-1348.	1.7	9
96	Thick film patterning by lift-off process using double-coated single photoresists. <i>Materials Letters</i> , 2012, 76, 117-119.	2.6	9
97	Control of Nanoplane Orientation in voBN for High Thermal Anisotropy in a Dielectric Thin Film: A New Solution for Thermal Hotspot Mitigation in Electronics. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 7456-7464.	8.0	9
98	Thermal Interface Materials Based on Vertically Aligned Carbon Nanotube Arrays: A Review. <i>Micro and Nanosystems</i> , 2019, 11, 3-10.	0.6	9
99	Process development and reliability for system-in-a-package using liquid crystal polymer substrate. , 0, , .		8
100	Study on the Reliability of Fast Curing Isotropic Conductive Adhesive. <i>ECS Transactions</i> , 2011, 34, 805-810.	0.5	8
101	Chemical Vapor Deposition of Vertically Aligned Carbon Nanotube Arrays: Critical Effects of Oxide Buffer Layers. <i>Nanoscale Research Letters</i> , 2019, 14, 106.	5.7	8
102	Manufacturing Grapheneâ€Encapsulated Copper Particles by Chemical Vapor Deposition in a Cold Wall Reactor. <i>ChemistryOpen</i> , 2019, 8, 58-63.	1.9	8
103	Bipolar electrochemical capacitors using double-sided carbon nanotubes on graphite electrodes. <i>Journal of Power Sources</i> , 2020, 451, 227765.	7.8	8
104	Graphene based thermal management system for battery cooling in electric vehicles. , 2020, , .		8
105	Combination of positive charges and honeycomb pores to promote MC3T3-E1 cell behaviour. <i>RSC Advances</i> , 2015, 5, 42276-42286.	3.6	7
106	Cooling hot spots by hexagonal boron nitride heat spreaders. , 2015, , .		7
107	Surface analysis of iron and steel nanopowder. <i>Surface and Interface Analysis</i> , 2018, 50, 1083-1088.	1.8	7
108	A general Weibull model for reliability analysis under different failure Criteria-application on anisotropic conductive adhesive joining technology. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2005, 28, 322-327.	1.4	6

#	ARTICLE	IF	CITATIONS
109	Computational fluid dynamics for effects of coolants on on-chip cooling capability with carbon nanotube micro-fin architectures. <i>Microsystem Technologies</i> , 2009, 15, 375-381.	2.0	6
110	Preparation of graphene/aligned carbon nanotube array composite films for thermal packaging applications. <i>Japanese Journal of Applied Physics</i> , 2019, 58, SHHH01.	1.5	6
111	Thermal conductivity enhancement of carbon@ carbon nanotube arrays and bonded carbon nanotube network. <i>Materials Research Express</i> , 2019, 6, 085616.	1.6	6
112	Improved Thermal Properties of Three-Dimensional Graphene Network Filled Polymer Composites. <i>Journal of Electronic Materials</i> , 2022, 51, 420-425.	2.2	6
113	Carbon Nanotubes in Electronics Interconnect Applications with a Focus on 3D-TSV Technology. <i>ECS Transactions</i> , 2012, 44, 683-692.	0.5	5
114	Enhanced cold wall CVD reactor growth of horizontally aligned single-walled carbon nanotubes. <i>Electronic Materials Letters</i> , 2016, 12, 329-337.	2.2	5
115	Vertically Aligned Graphene-based Thermal Interface Material with High Thermal Conductivity. , 2018, , .		5
116	Highly Thermal Conductive and Electrically Insulated Graphene Based Thermal Interface Material with Long-Term Reliability. , 2019, , .		5
117	Multiple growth of graphene from a pre-dissolved carbon source. <i>Nanotechnology</i> , 2020, 31, 345601.	2.6	5
118	Highly Thermally Conductive and Light Weight Copper/Graphene Film Laminated composites for Cooling Applications. , 2018, , .		4
119	Atomic Layer Deposition of Buffer Layers for the Growth of Vertically Aligned Carbon Nanotube Arrays. <i>Nanoscale Research Letters</i> , 2019, 14, 119.	5.7	4
120	Ontology for the anisotropic conductive adhesive interconnect technology for electronics packaging applications. , 2005, , .		3
121	Millimeter-wave ultra-wideband bandpass filter based on liquid crystal polymer substrates for automotive radar systems. <i>Microwave and Optical Technology Letters</i> , 2008, 50, 2276-2280.	1.4	3
122	Experimental Investigation and Micropolar Modelling of the Anisotropic Conductive Adhesive Flip-Chip Interconnection. <i>Journal of Adhesion Science and Technology</i> , 2008, 22, 1717-1731.	2.6	3
123	Molecular Gun Composed of Carbon Nanotube. <i>Journal of Computational and Theoretical Nanoscience</i> , 2011, 8, 1716-1719.	0.4	3
124	Synthesis of a Graphene Carbon Nanotube Hybrid Film by Joule Self-Heating CVD for Thermal Applications. , 2018, , .		3
125	Comparison of isothermal mechanical fatigue properties of lead free solder joints and bulk solders. , 2003, , .		2
126	Integrated Capacitors and Resistors on Liquid Crystal Polymer Substrate. , 2005, , .		2

#	ARTICLE	IF	CITATIONS
127	Study on the Reliability of Nano-Structured Polymer-Metal Composite for Thermal Interface Material. ECS Transactions, 2011, 34, 991-995.	0.5	2
128	Characterization of CNT Enhanced Conductive Adhesives in Terms of Thermal Conductivity. ECS Transactions, 2012, 44, 1011-1017.	0.5	2
129	Effect of substrates and underlayer on CNT synthesis by plasma enhanced CVD. Advances in Manufacturing, 2013, 1, 236-240.	6.1	2
130	Characterization of nano-enhanced interconnect materials for fine pitch assembly. Soldering and Surface Mount Technology, 2014, 26, 12-17.	1.5	2
131	Development and characterization of graphene enhanced thermal conductive adhesives. , 2016, , .		2
132	Estimating the constitutive behaviour of sintered silver nanoparticles by nanoindentation. , 2018, , .		2
133	A Critical Assessment of Nano Enhanced Vapor Chamber Wick Structures for Electronics Cooling. , 2021, , .		2
134	Graphene Oxide and Nitrogen-Doped Graphene Coated Copper Nanoparticles in Water-Based Nanofluids for Thermal Management in Electronics. Journal of Nanofluids, 2022, 11, 125-134.	2.7	2
135	Implementation of the Internet course on conductive adhesives for electronics packaging. , 0, , .		1
136	Reliability investigations for encapsulated isotropic conductive adhesives flip chip interconnection. , 0, , .		1
137	Design of 50â€“70ÂGHz Planar Wideband Bandpass Filter on Liquid Crystal Polymer Substrate. Journal of Infrared, Millimeter, and Terahertz Waves, 2009, 30, 183-189.	2.2	1
138	Design of Printed Monopole Antennas on Liquid Crystal Polymer Substrates. Journal of Infrared, Millimeter, and Terahertz Waves, 2010, 31, 469.	2.2	1
139	Study on the bimodal filler influence on the effective thermal conductivity of thermal conductive adhesive. Microsystem Technologies, 2011, 17, 93-99.	2.0	1
140	Experimental study on electrical properties and stability of CNT bumps in high density interconnects. , 2013, , .		1
141	Critical Atomic-level Processing Technologies: Remote Plasma-enhanced Atomic Layer Deposition and Atomic Layer Etching. Micro and Nanosystems, 2018, 10, 76-83.	0.6	1
142	Effect of Boron Nitride Particle Geometry on the Thermal Conductivity of a Boron Nitride Enhanced Polymer Composite Film. , 2019, , .		1
143	Analysis of heat dissipation characteristics of three-dimensional graphene-carbon nanotube composite structures. , 2020, , .		1
144	Foreword - Fifth international IEEE symposium on high density packaging and component failure analysis (HDP'02). IEEE Transactions on Electronics Packaging Manufacturing, 2002, 25, 251-252.	1.4	0

#	ARTICLE	IF	CITATIONS
145	Study on thermomechanical reliability of a tunable light modulator. <i>Microelectronics Reliability</i> , 2004, 44, 779-785.	1.7	0
146	Effect of encapsulation on OLED characteristics with anisotropic conductive adhesive. , 2008, , .		0
147	Flip Chip Assembly Using Carbon Nanotube Bumps and Anisotropic Conductive Adhesive Film. <i>ECS Transactions</i> , 2010, 27, 825-830.	0.5	0
148	Measurement of Dielectric Properties of Ultrafine BaTiO ₃ Using an Organic-Inorganic Composite Method. <i>Journal of Electronic Materials</i> , 2015, 44, 2300-2307.	2.2	0
149	Reliability study on high thermally conductive graphene film as heat spreader in electronics cooling applications. , 2018, , .		0
150	Effect of Fiber Concentration on Mechanical and Thermal Properties of a Solder Matrix Fiber Composite Thermal Interface Material. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019, 9, 1045-1053.	2.5	0
151	Graphene-coated copper nanoparticles for thermal conductivity enhancement in water-based nanofluid. , 2019, , .		0
152	Experimental Measurements of Thermal Performances of Carbon Nanomaterial with Vertical Structures in Hotspot Heat Dissipation *. , 2019, , .		0
153	Effect of space environment on the reliability of sintered silver nanoparticles reinforced by SiC particles. , 2019, , .		0
154	RF Properties of Carbon Nanotube / Copper Composite Through Silicon Via Based CPW Structure for 3D Integrated Circuits. , 2019, , .		0
155	Thermally Conductive Graphene Film/Indium/Aluminum Laminated Composite by Vacuum Assisted Hot-pressing. , 2020, , .		0
156	Exploring Graphene Coated Copper Nanoparticles as a multifunctional Nanofiller for Micro-Scaled Copper Paste. , 2021, , .		0
157	Thermal Analysis of An Au/Pt/Ti-Based Microheater. , 2021, , .		0
158	Synergistic Toughening of Graphene Films by Addition of Hydroxylated Carbon Nanotube. , 2021, , .		0
159	Fabrication and Characterization of Graphene/polyimide Composite Film. , 2021, , .		0
160	Highly Thermally Conductive Substrate Based on Graphene Film. , 2021, , .		0
161	Thermal Properties of Laser-induced Graphene Films Photothermally Scribed on Bare Polyimide Substrates. , 2021, , .		0
162	Thermal Properties of Laser Reduced Graphene Oxide Films. , 2021, , .		0

#	ARTICLE	IF	CITATIONS
163	Transparent heaters based on CVD grown few-layer graphene. Journal of Materials Science: Materials in Electronics, 2022, 33, 3586-3594.	2.2	0